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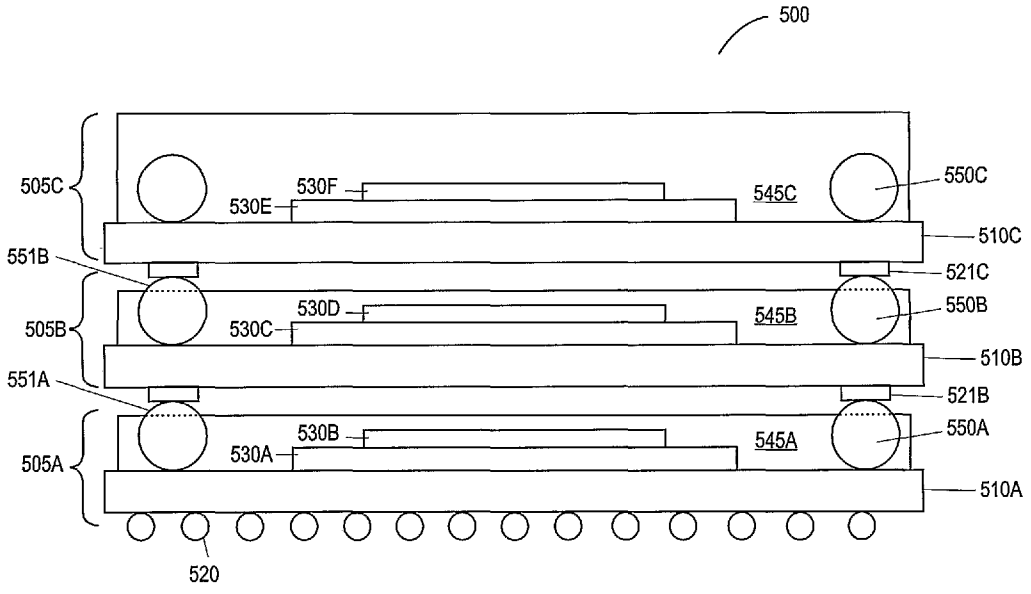
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(54) **Title:** METHODS AND APPARATUSES FOR PROVIDING STACKED-DIE DEVICES



(57) **Abstract:** Methods and apparatuses to provide a stacked-die device comprised of stacked sub-packages. For one embodiment of the invention, each sub-package has interconnections formed on the die-side of the substrate for interconnecting to another sub-package. The dies and associated wires are protected by an encapsulant leaving an upper portion of each interconnection exposed. For one embodiment of the invention the encapsulant is a stencil-printable encapsulant and the upper portion of the interconnection is exposed by use of a patterned stencil during application of the encapsulant.

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